

PRODUCT DATA SHEET

CORE 230 No-Clean Cored Wire Solder



Introduction

CORE 230 wire solder is cored with a no-clean flux that is fully compatible with Indium Corporation's NC-SMQ®230 Pb-free solder paste. It contains a heat-stabilized rosin that provides excellent wetting and solder spread on various metallizations used in Pb-free assembly processes.

Features

- Optimized for use with Pb-free assembly processes
- Fast and excellent wetting to Pb-free surface finishes including immersion Ag, ENIG, and OSP
- Bellcore GR-78 compliant
- Resistant to charring
- Minimal spattering and low odor

Product Description

Spool Weight	.020" (0.5mm) or greater .015" (0.375mm) or smaller	500g or 1 lb 125g or ¼ lb
Flux Percentage	2.7–3.2% by weight	
Available Alloys	Per J-STD-006 Variation C 95.5Sn/3.8Ag/0.7Cu	

Wire Diameters

CORE 230 Wire Solder Length per Spool	
Wire Diameter	95.5Sn/3.8Ag/0.7Cu
.010" ± .002" (.254mm ± .051mm)	1,996ft (608m)
.015" ± .002" (.381mm ± .051mm)	2,087ft (636m)
.020" ± .002" (.508mm ± .051mm)	1,174ft (357.7m)
.032" ± .002" (.813mm ± .051mm)	459ft (139.8m)

Values are only approximate. Actual lengths will vary.

Bellcore and J-STD Tests and Results

Test	Result	Test	Result
J-STD-004 (IPC-TM-650)		Bellcore GR-78	
Flux Type Classification	ROL1	SIR	Pass
Flux Induced Corrosion (Copper Mirror)	Pass	<i>All information is for reference only. Not to be used as incoming product specifications.</i>	
Presence of Halide Fluoride Spot Test	Pass		
Corrosion	Pass		
SIR	Pass		

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Residue Removal

The flux in **CORE 230** is formulated for use in a no-clean assembly process. If cosmetics or the end use application requires removal of the post reflow residue, standard rosin-based residue removal techniques can be utilized. This includes, but is not limited to: spray-in air, immersion spray, vapor degreasing, or ultrasonic type cleaning processes.

Storage

CORE 230 has a shelf life of 3 years when stored in a dry, non-corrosive environment such as a low-humidity dry cabinet. Direct sunlight, excessive humidity, and storage near heat sources should be avoided.

Technical and Customer Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Material Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>

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